

Type number	Package	Package description	Total product weight
74LVC4245ABQ-Q100	SOT815-1	DHVQFN24	50.45430 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935305304118	4	1	260	30 s	1	240	20 s	3	Nijmegen, Netherlands; Suzhou, China; Bangkok, Thailand	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.10188	80.10000	0.20192
	Polymer	Resin system	Proprietary	0.02531	19.90000	0.05017
		subTotal		0.12719	100.00000	0.25209
Die	Doped silicon	Silicon (Si)	7440-21-3	0.61828	100.00000	1.22542
		subTotal		0.61828	100.00000	1.22542
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	19.07808	97.47000	37.81259
		Iron (Fe)	7439-89-6	0.46976	2.40000	0.93106
		Phosphorous (P)	7723-14-0	0.00587	0.03000	0.01164
		Zinc (Zn)	7440-66-6	0.01957	0.10000	0.03879
		subTotal		19.57328	100.00000	38.79408
Mould Compound	Additive	Non hazardous	Proprietary	0.85852	2.91000	1.70158
	Filler	Silica -amorphous-	7631-86-9	1.02963	3.49000	2.04073
		Silica fused	60676-86-0	25.02394	84.82000	49.59725
	Pigment	Carbon black	1333-86-4	0.04720	0.16000	0.09356
	Polymer	1.4-bis(methoxymethyl)benzene/phenol copolymer	26834-02-6	0.31863	1.08000	0.63151
		Epoxy resin system	Proprietary	0.46909	1.59000	0.92973
		Phenolic resin	Proprietary	0.66380	2.25000	1.31565
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	1.09159	3.70000	2.16352
subTotal			29.50241	100.00000	58.47353	
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.00497	1.00000	0.00985
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.45214	91.00000	0.89614
		Palladium (Pd)	7440-05-3	0.03975	8.00000	0.07878
		subTotal		0.49686	100.00000	0.98477
Wire	Pure metal	Copper (Cu)	7440-50-8	0.13158	96.55000	0.26080
	Pure metal layer	Gold (Au)	7440-57-5	0.00048	0.35000	0.00095
		Palladium (Pd)	7440-05-3	0.00422	3.10000	0.00837
		subTotal		0.13628	100.00000	0.27012

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